



YES-G1000 Plasma Cleaning System

For Wire Bond Surface Preparation and Gentle Cleaning Applications

Specifications

Hardware	
Clean Room Compatibility	Class 10
Operation Temperature	20 – 100 °C
N ₂ Flow Rate	1.7 SCFM
Process Gas Flow Rate	20-50 SCCM average
Interior Chamber Dimensions	45.72 cm (W) x 45.72 cm (D) x 30.48 cm (H) (18" x 18" x 12")
Chamber Process Area	931 in ² or 233 in ² per shelf
Overall System Dimensions	59.69 cm (W) x 71.12 cm (D) x 113.284 cm (H) (23.5" x 28" x 44.6")
Chamber Material	6061-T6 aluminum
Process Gas Inputs	3 standard, 4 th optional
Mass Flow Controllers	Optional, up to 3 for gas mixing
SEMI™ Compliance	S2/S8
Software	
Number of Recipes	12 with load/save/loop/link capability
Range of Exposure Time	0-1200 seconds (20 minutes)
Resolution of Timer Setting	1 second
Performance	
RF Plasma Power	0-1000 watts @ 550 VAC, selectable power
RF Leakage Magnetic	0.6 mA/m, 4.15 x 10 ⁻⁷ A ² /m ² Average
RF Leakage Electrical	1.6 V/m, 4.2 V ² /m ² Average
Nitrogen Consumption	0 SCF idle, 6.8 SCF peak, 1.7 SCF average
Power Consumption with Pump	375W idle, 1000W peak, 640W average
Reactant Gas Consumption	0 SCF idle, 20-50 SCCM
Heat Emission	920 watts average
Additional	
Power Requirements	200-250V, 20 amps, 50/60 Hz, 1 phase
System Weight	158.76 kg (350 lbs)



Contact Us

When you're ready to run process tests, a demonstration can be arranged using your chemicals and samples. Call +1 925-373-8353 (worldwide), 1-888-YES-3637 (US toll free), or visit us online at www.yieldengineering.com.

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